AIC1714



FEATURES

- Low Power Consumption, 0.78W(TO-92 Package)
- Output Short Circuit Protected.
- Wide Operating Voltage up to -13V.
- Low 6µA Quiescent Supply Current
- Stable with 1µF COUT
- -5.0V, -3.3V, or -3.0V Output Voltage
- Space-Saving Package: TO-92 or SOT-89

APPLICATIONS

- LCD display
- Cameras

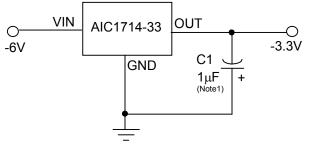
Negative Voltage Regulator

DESCRIPTION

The AIC1714 is 3-terminal negative voltage regulators, which transform from negative supply voltage. The high capacity and long service life of battery, which result from the characteristics of AIC1714 - low quiescent current consumed and low dropout voltage needed, perfectly meet the requirement for battery-powered portable devices as well as LCD displays.

The AIC1714 is available in several preset output voltage versions (-5.0V, -3.3V, and -3.0V) with short circuit protection and offered in TO-92 and SOT-89 packages.

TYPICAL APPLICATION CIRCUIT

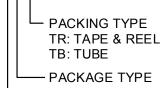


Negative Voltage Regulator



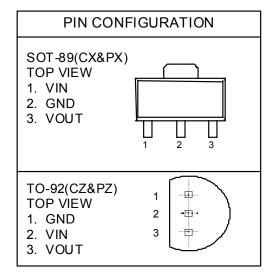
ORDERING INFORMATION

AIC1714-XXXXXX



X: SOT-89 Z: TO-92

C: Commercial P: Lead Free Commercial G:Green Pqckage



Example: AIC1714-30CXTR

→ -3.0V Version, in SOT-89 Package & Tape & Reel Packing Type

AIC1714-30PXTR

→ -3.0V Version, in SOT-89 Lead Free Package
& Tape & Reel Packing Type

AIC1714-30GXTR

→ -3.0V Version, in SOT-89 Green Package &

Tape & Reel Packing Type

• SOT89 Marking

Part No.	СХ	PX	GX
AIC1714-30	AP30	AP30P	AP30G
AIC1714-33	AP33	AP33P	AP33G
AIC1714-50	AP50	AP50P	AP50G

ABSOLUTE MAXIMUM RATINGS

Supply Voltage		13V	
Operating Temperature Range		- 40°C~85°C	
Storage Temperature Range		- 65°C~150°C	
Maximum Junction Temperature		125°C	
Lead Temperature (Soldering) 10 sec.		260°C	
Thermal Resistance (Junction to Case)	SOT-89	30°C /W	
	TO-92	120°C /W	
Thermal Resistance (Junction to Ambient)	SOT-89	160°C/W	
(Assume no ambient airflow, no heatsink)	TO-92	150°C/W	
Absolute Maximum Ratings are those va	alues beyond w	hich the life of a device may	be impaired.





TEST CIRCUIT

Refer to "TYPICAL APPLICATION CIRCUIT"

ELECTRICAL CHARACTERISTICS (V_{IN}= -6.0V, T_J=25°C, unless otherwise specified.) (Note2)

PARAMETER	TEST CONDITIONS		SYMBOL	MIN.	TYP.	MAX.	UNIT
		AIC1714-30		-2.95	-3.0	-3.05	V
Output Voltage	Ι _{ΟUT} =300μΑ	AIC1714-33	Vout	-3.25	-3.3	-3.35	V
		AIC1714-50		-4.93	-5.0	-5.07	V
Load Regulation	I _{OUT} =0~5mA		ΔV_{OUT}		20	100	mV
I/O Voltage Difference	Ι _{ΟUT} =300μΑ		VDIFF		50	200	mV
Supply Current	I _{OUT} =0		I _{IN}		6	12	μA
Input Stability			$\frac{\Delta V \text{out}}{\Delta V \text{in} \bullet V \text{out}}$		0.05		%/ V
Temperature Coefficient	-25°C~85°C		Т _С		50		ppm
Output Short Circuit Current	R _{LOAD} =0			15	24		mA

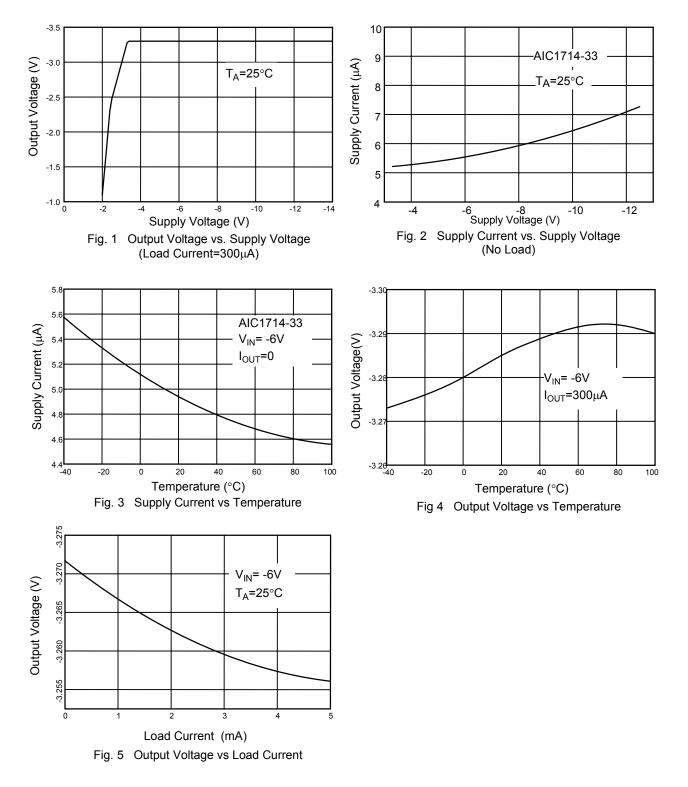
Note 1: To avoid output oscillation, aluminum electrolytic output capacitor is recommended and ceramic capacitor is not suggested.

Note 2: Specifications are production tested at $T_A = 25^{\circ}C$. Specifications over the -40°C to 85°C operating temperature range are assured by design, characterization and correlation with Statistical Quality Controls (SQC).





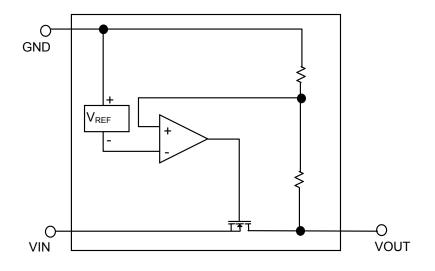
TYPICAL PERFORMANCE CHARACTERISTICS



4



BLOCK DIAGRAM



PIN DESCRIPTIONS

VOUT PIN - Output pin. GND PIN - Power GND. VIN PIN - Power Supply Input.

APPLICATION INFORMATION INPUT-OUTPUT CAPACITORS

The linear regulator requires the output capacitor to maintain stability. An aluminum electrolytic output capacitor at 1μ F is recommended for most AIC1714 applications. A 0.1 μ F input capacitor (or greater) should be placed from the AIC1714 input to ground if the lead inductance between the input and the power source exceeds 500nH.

POWER DISSIPATION

The maximum power dissipation of AIC1714 depends on the thermal resistance of its case and circuit board, the temperature difference between the die junction and ambient air, and the rate of airflow. The rate of temperature rise is greatly affected by the mounting pad configuration on the PCB, the board material, and the ambient temperature. When the IC

mounting with good thermal conductivity is used, the junction temperature will be low even when large power dissipation applies.

The power dissipation across the device is

$$\mathsf{P} = \mathsf{I}_{\mathsf{OUT}} (\mathsf{V}_{\mathsf{IN}} - \mathsf{V}_{\mathsf{OUT}}).$$

The maximum power dissipation is:

$$P_{MAX} = \frac{(T_{J-max} - T_A)}{R\theta_{JA}}$$

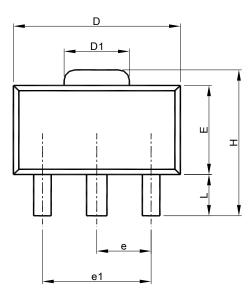
Where T_{J-max} is the maximum allowable junction temperature (125°C), and T_A is the ambient temperature suitable in application.

As a general rule, the lower temperature is, the better reliability of the device is. So the PCB mounting pad should provide maximum thermal conductivity to maintain low device temperature.



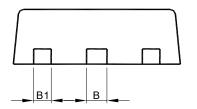
PHYSICAL DIMENSIONS (unit: mm)

• SOT-89



	S Y	SOT-	89	
M B		MILLIMETERS		
	O L	MIN.	MAX.	
	А	1.40	1.60	
	В	0.44	0.56	
	B1	0.36	0.48	
	С	0.35	0.44	
	D	4.40	4.60	
	D1	1.50	1.83	
	Е	2.29	2.60	
	е	1.50 BSC 3.00 BSC		
	e1			
	Н	3.94	4.25	
	L	0.89	1.20	

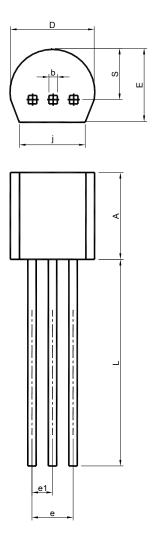
С



- Note: 1. Refer to JEDEC TO-243AA.
 - 2. Dimension "D" does not include mold flash, protrusions or gate burrs. Mold flash, protrusion or gate burrs shall not exceed 6 mil per side.
 - 3. Dimension "E" does not include inter-lead flash or protrusions.
 - 4. Controlling dimension is millimeter, converted inch dimensions are not necessarily exact.



• TO-92 (BAG)



	TO-9	2
S Y		
M B	MILLIM	ETERS
B O L	MIN.	MAX.
А	4.32	5.33
b	0.36	0.47
D	4.45	5.20
Е	3.18	4.19
е	2.42	2.66
e1	1.15	1.39
j	3.43	
L	12.70	
S	2.03	2.66

Note: 1. Refer to JEDEC TO-226.

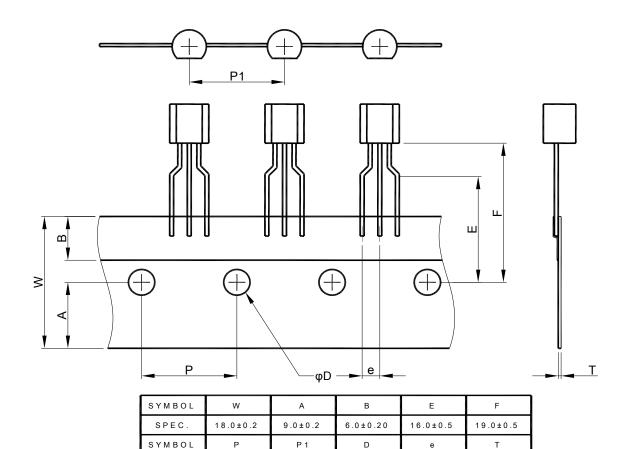
- Dimension "D" does not include mold flash, protrusions or gate burrs. Mold flash, protrusion or gate burrs shall not exceed 6 mil per side.
- 3. Dimension "A" does not include inter-lead flash or protrusions.
- 4. Controlling dimension is millimeter, converted inch dimensions are not necessarily exact.



• TO-92 (Tape & Reel)

SPEC

12.7 BSC



Note:

Information provided by AIC is believed to be accurate and reliable. However, we cannot assume responsibility for use of any circuitry other than circuitry entirely embodied in an AIC product; nor for any infringement of patents or other rights of third parties that may result from its use. We reserve the right to change the circuitry and specifications without notice.

12.7 BSC

4.0±0.2

2.5 BSC

0.6±0.1

Life Support Policy: AIC does not authorize any AIC product for use in life support devices and/or systems. Life support devices or systems are devices or systems which, (I) are intended for surgical implant into the body or (ii) support or sustain life, and whose failure to perform, when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury to the user.